AUTOMOTIVI GRADE

RoHS

COMPLIANT

HALOGEN

FREE



## Vishay General Semiconductor

# **Surface Mount Trench MOS Barrier Schottky Rectifiers**

# TMBS® eSMP® Series Top view Bottom view SMF (DO-219AB)

PRIMARY CHARACTERISTICS			
I <sub>F(AV)</sub>	2.0 A		
$V_{RRM}$	150 V		
I <sub>FSM</sub>	40 A		
$V_F$ at $I_F = 2 \text{ A } (T_A = 125 \text{ °C})$	0.69 V		
T <sub>J</sub> max.	175 °C		
Package	SMF (DO-219AB)		

Diode variations

#### **FEATURES**





· Ideal for automated placement

· Low forward voltage drop, low power losses

 Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

• Wave and reflow solderable

AEC-Q101 qualified available
 Automotive avalation and by bean R/I

- Automotive ordering code: base P/NHM3

 Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

#### **TYPICAL APPLICATIONS**

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

#### **MECHANICAL DATA**

Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: color band denotes the cathode end

<b>MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)			
PARAMETER	SYMBOL	V2FM15	UNIT
Device marking code		2MC	
Maximum repetitive peak reverse voltage	$V_{RRM}$	150	V
Maximum average forward rectified current (fig.1)	I <sub>F(AV)</sub> (1)	2.0	Α
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	40	А
Operating junction temperature range	T <sub>J</sub> <sup>(2)</sup>	-40 to +175	°C
Storage temperature range	T <sub>STG</sub>	-55 to +175	

#### Notes

Single

<sup>(1)</sup> Free air, mounted on FR4 PCB, 2 oz. standard footprint

The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ 



<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 1.0 A	- T <sub>A</sub> = 25 °C		0.87	-	V
	I <sub>F</sub> = 2.0 A		V <sub>F</sub> (1)	1.28	1.46	
	I <sub>F</sub> = 1.0 A	T <sub>A</sub> = 125 °C	V <sub>F</sub> (')	0.60	-	
	I <sub>F</sub> = 2.0 A		-	0.69	0.77	
Reverse current	V 100 V	T <sub>A</sub> = 25 °C		0.3	-	
	V <sub>R</sub> = 100 V	T <sub>A</sub> = 125 °C	I <sub>R</sub> <sup>(2)</sup>	300	-	
	V <sub>R</sub> = 150 V	T <sub>A</sub> = 25 °C	IR (-)	-	50	μΑ
		T <sub>A</sub> = 125 °C	-	550	2000	
Typical junction capacitance	4.0 V, 1 MHz		CJ	90	-	pF

#### Notes

 $^{(1)}$  Pulse test: 300  $\mu$ s pulse width, 1 % duty cycle

 $^{(2)}$  Pulse test: Pulse width  $\leq 5 \text{ ms}$ 

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °c unless otherwise noted)				
PARAMETER SYMBOL V2FM15			UNIT	
Typical thermal resistance	R <sub>0</sub> JA (1)(2)	125	°C/W	
	R <sub>0JM</sub> (2)	26	C/VV	

#### Notes

 $^{(1)}$  The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ 

(2) Device mounted on FR4 PCB, 2 oz. standard footprint, thermal resistance  $R_{\theta JA}$  – junction-to-ambient; thermal resistance  $R_{\theta JM}$  – junction-to-mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V2FM15-M3/H	0.015	Н	3000	7" diameter plastic tape and reel
V2FM15-M3/I	0.015	I	10 000	13" diameter plastic tape and reel
V2FM15HM3/H (1)	0.015	Н	3000	7" diameter plastic tape and reel
V2FM15HM3/I (1)	0.015	I	10 000	13" diameter plastic tape and reel

#### Note

(1) AEC-Q101 qualified



### **RATINGS AND CHARACTERISTICS CURVES** (T<sub>A</sub> = 25 °C unless otherwise noted)

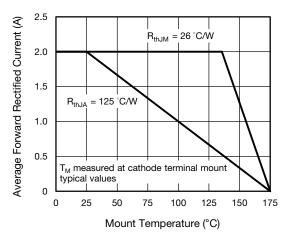


Fig. 1 - Maximum Forward Current Derating Curve

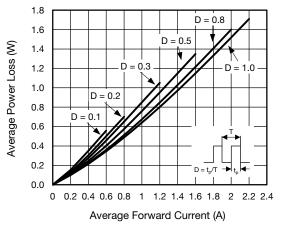


Fig. 2 - Average Power Loss Characteristics

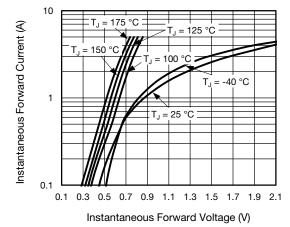


Fig. 3 - Typical Instantaneous Forward Characteristics

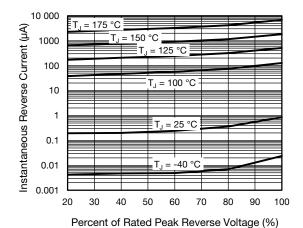


Fig. 4 - Typical Reverse Leakage Characteristics

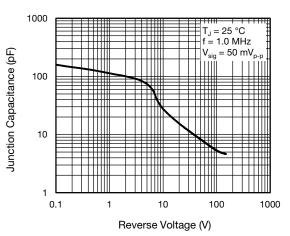


Fig. 5 - Typical Junction Capacitance

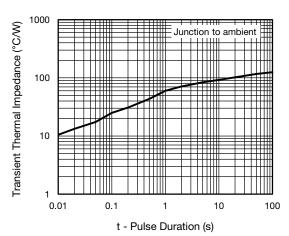
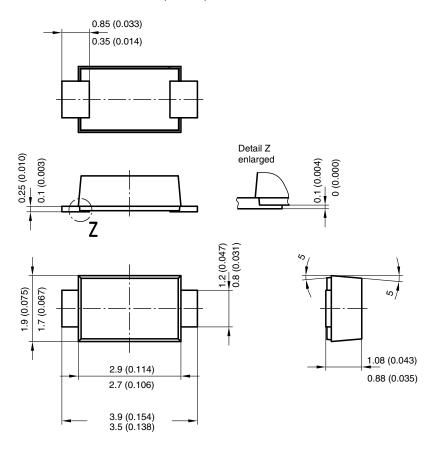


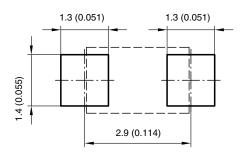
Fig. 6 - Typical Transient Thermal Impedance



#### PACKAGE OUTLINE DIMENSIONS in millimeters (inches)



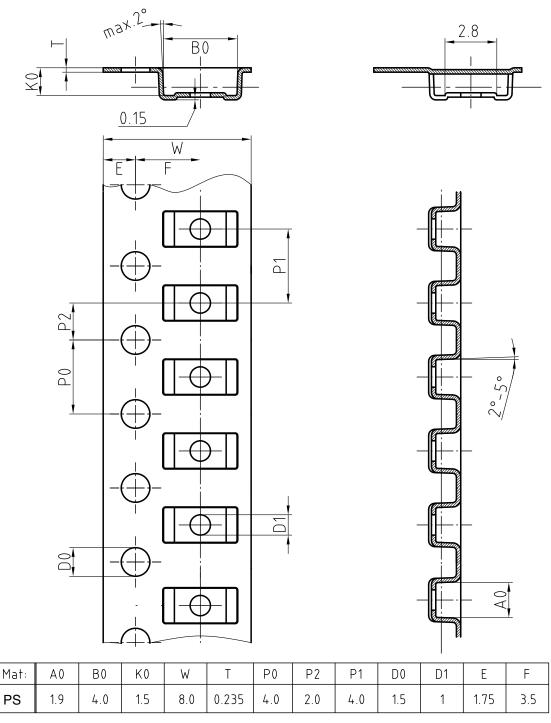
#### Foot print recommendation:



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#### **BLISTERTAPE DIMENSIONS** in millimeters: **SMF (DO-219AB)**



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